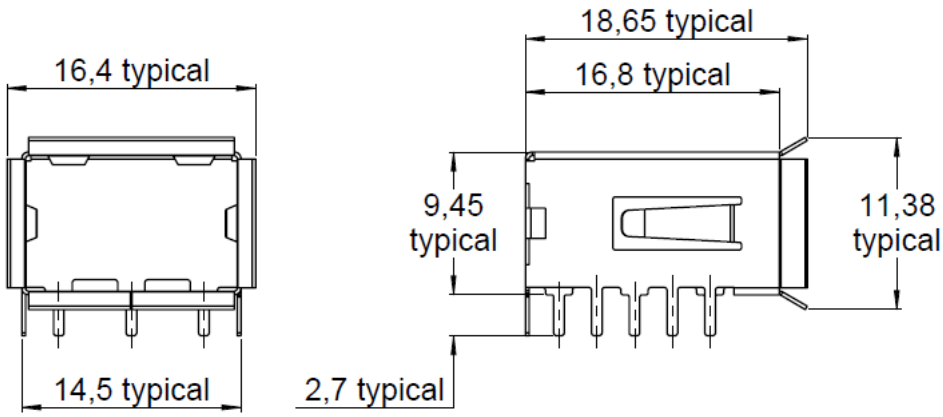
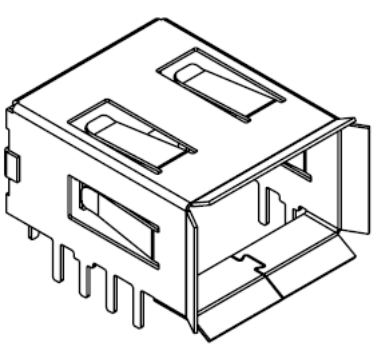
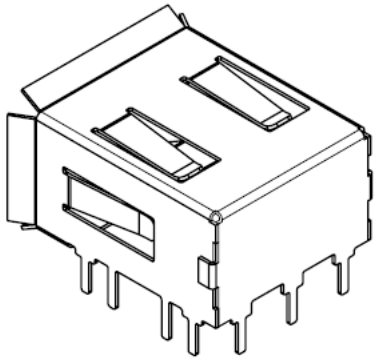
PAGE 1/7	ISSUE 11-01-19B	SERIES OCTIS	PART NUMBER **OCTI140500**







All dimensions are in mm. Tolerances according ISO 2768 m-H.

DESCRIPTION

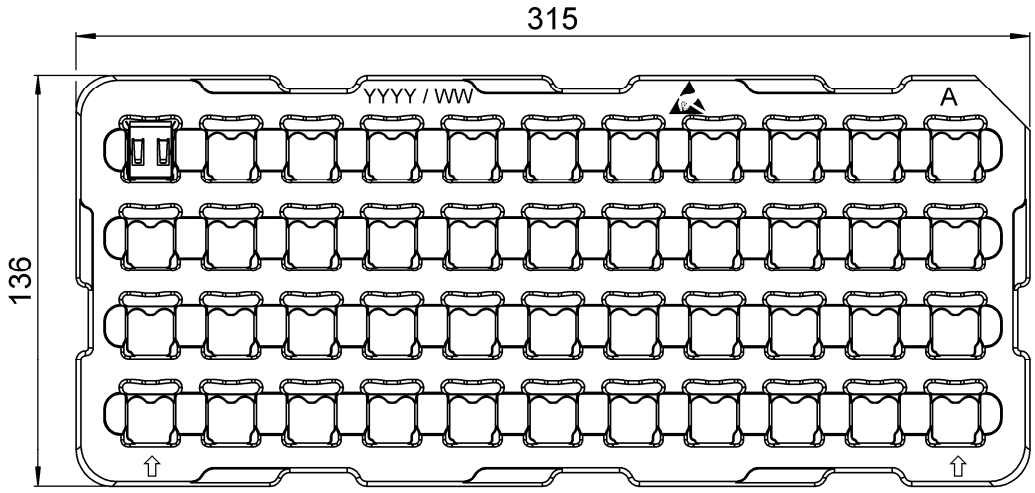
REP	COMPONENT	MATERIALS	PLATING
1	**SFP Shielding cage**	**BRASS**	**NiSn**

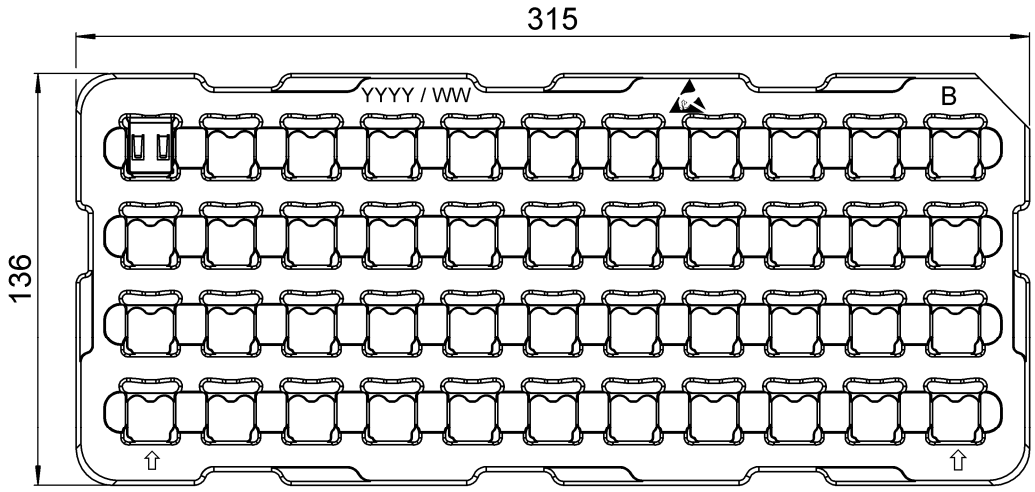
GENERAL CHARACTERISTICS

Mechanical		
Mating endurance (cycles)	IEC 61300-2-2	100
Vibration	IEC 61300-2-1	-
Weight (g)	-	1,6530
Environmental		
Operating temperature (°C)	IEC 61300-2-22	-40 / +85
Storage temperature (°C)	IEC 61300-2-22	-65 / +85
RoHS	-	Compliant
Others		
-	-	ESD approved
Handling	-	Only with gloves

PACKAGING:

Packaging in Hot Formed Tray

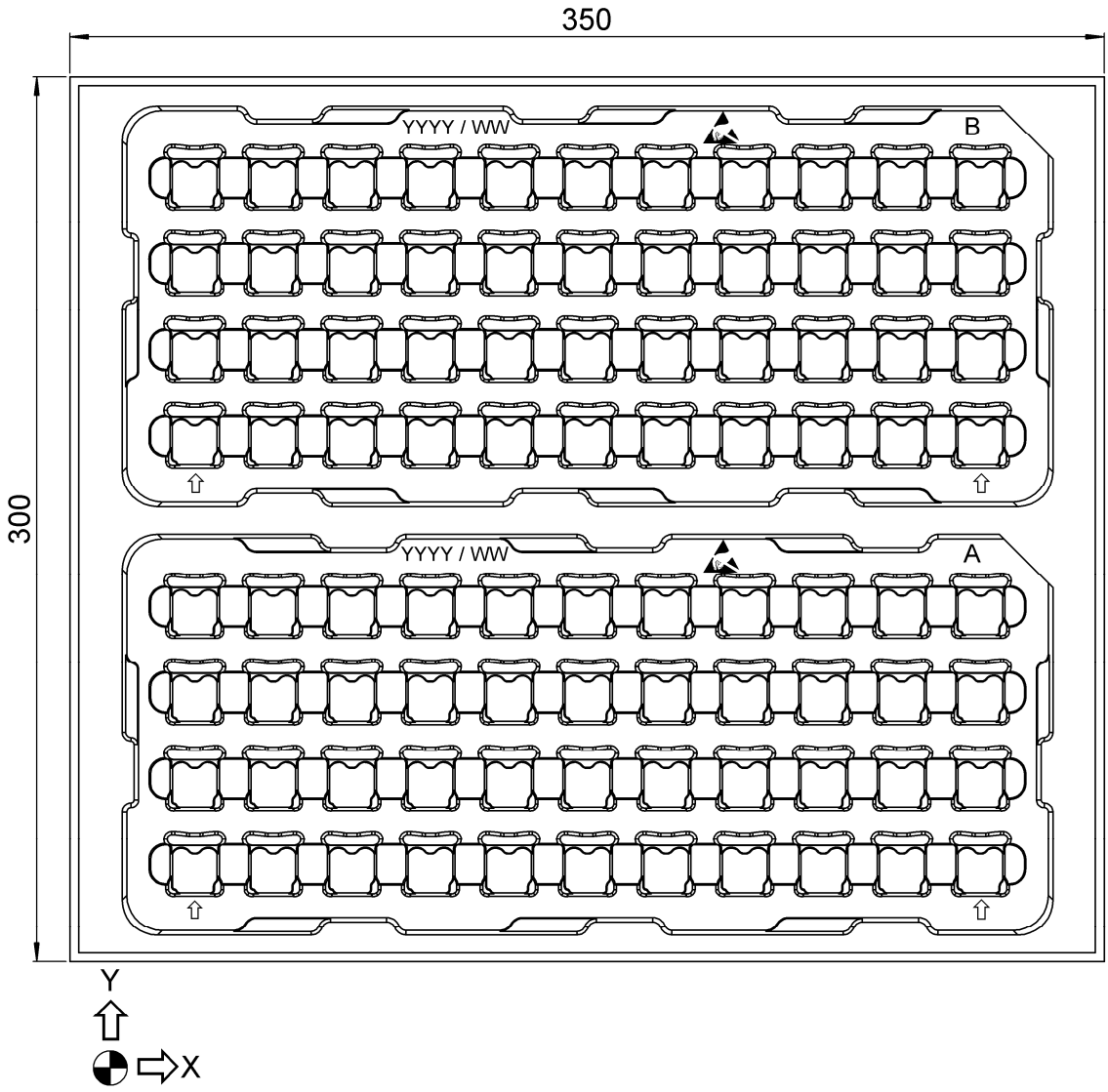




Tray Information:
44 pcs by Tray
Color: tray A in black and tray B in translucent
YYYY: manufacturing year
WW: manufacturing week
: ESD symbol

PACKAGING:

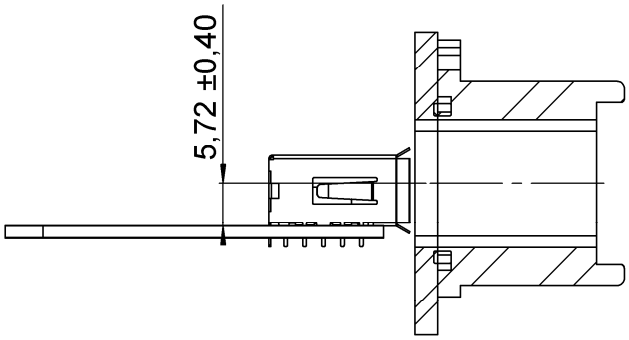
Packaging in the box

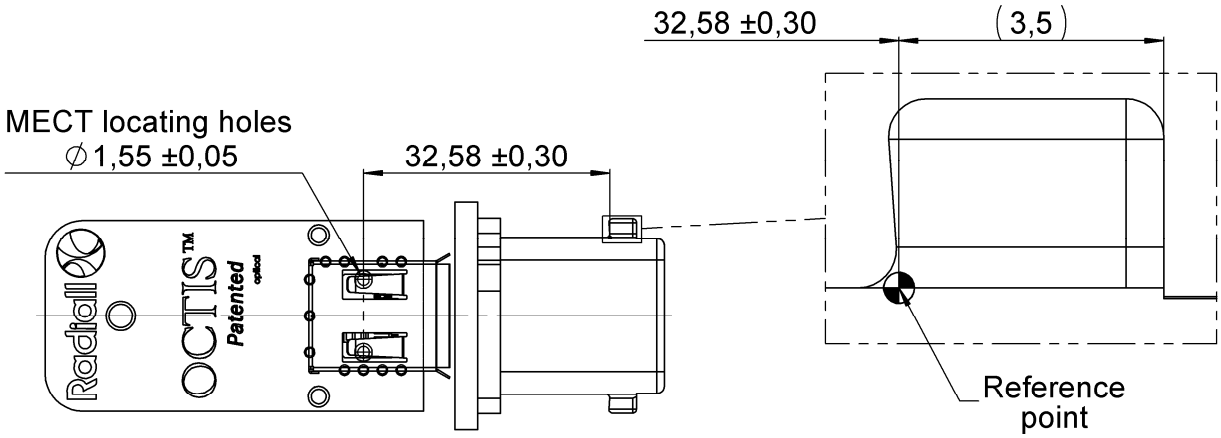


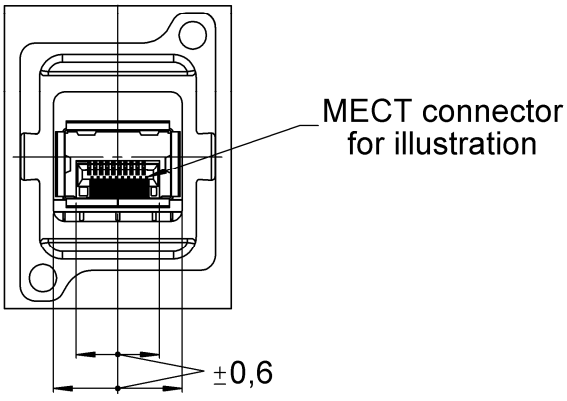
Packaging Information:
1144 pcs by Box
X pitch = 26.6 mm
Y pitch = 26.6 mm
Z dimension = 18 mm
Tray A and tray B stocked alternatively
Hot formed trays fitted in a ESD bag and in card board box

POSITIONNING AND PATTERN DEFINITION

OCTIS SFP Version with universal receptacle



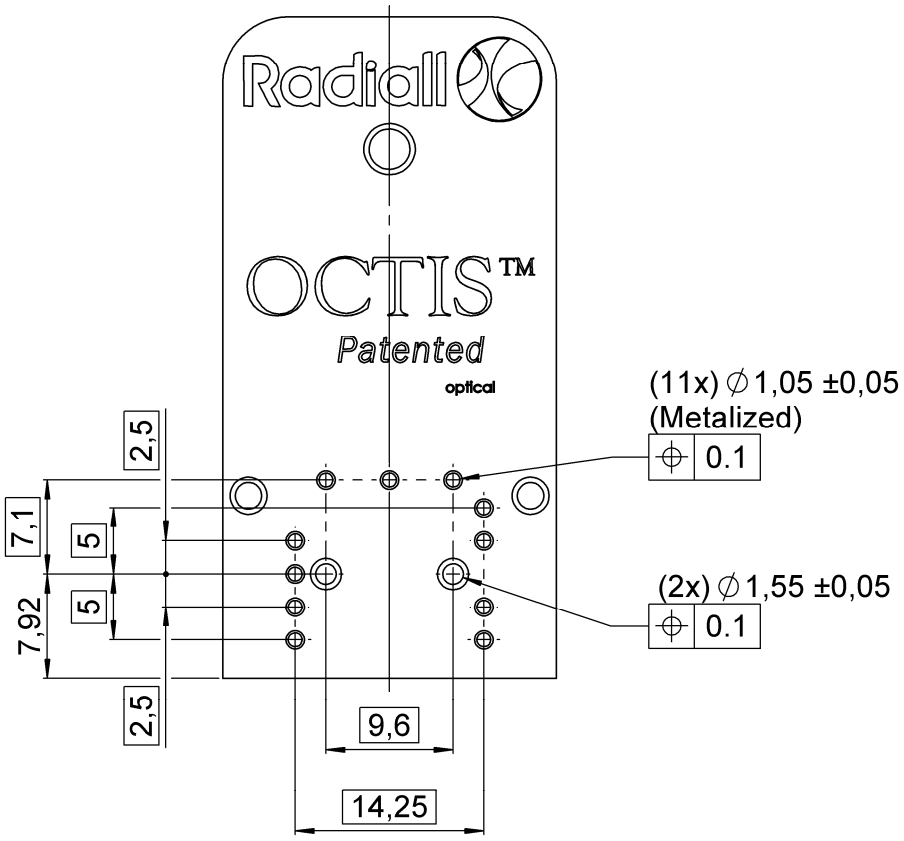




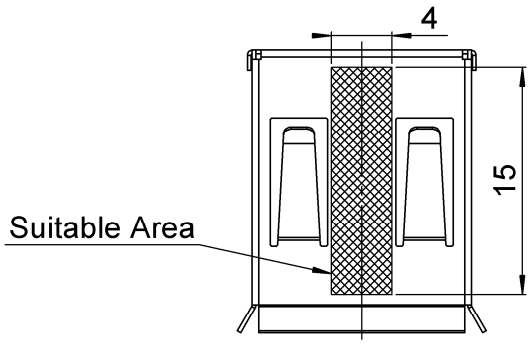
Centering of the shielding
cage vs receptacle cavity

For use with OCTIS Plug Kit p/n OCTI.117.500

FOOT/PRINT
(General Tolerances for PCB +/- 0,1 mm)



SUITABLE AREA FOR PICK & PLACE VACUUM NOZZLE



SOLDER PROCEDURE*

1. Deposit solder paste (Sn Ag4 Cu0.5) on solder pads / mounting area by screen printing application. We recommend a low residue flux. Verify that the edges of the pads are clean.

2. Place the component on the mounting area with a pick & place machine.
   A video camera is recommended for a good positioning of the component.
   Adhesive agents must not be used on the component.

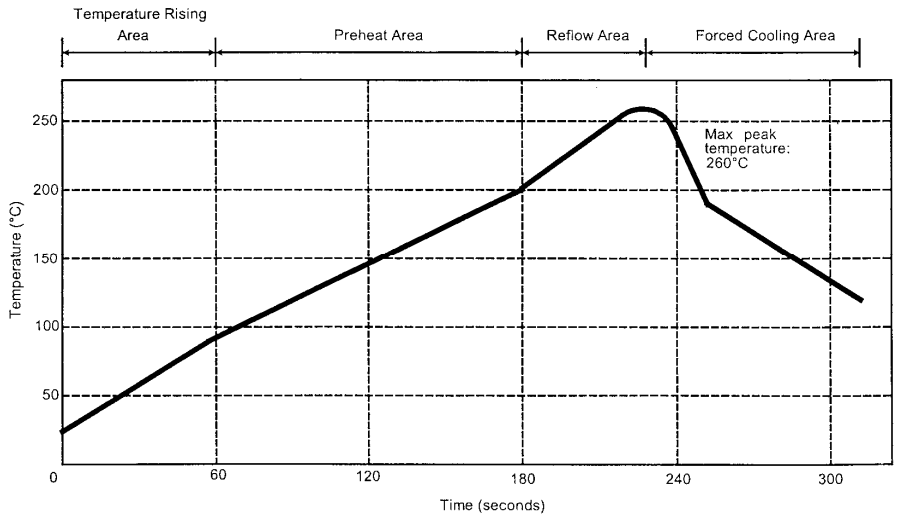
3. This process of soldering has been tested with a convection oven.
   Below please find the typical soldering profile to use.

4. Optional cleaning of printed circuit board.

5. Check solder joints and position of the component by visual inspection.

Note: When soldering a receptacle, no plug should be mated to the receptacle before completion of this procedure.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 to 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

*Typical data for reflow process. Alternatively, wave soldering is also possible